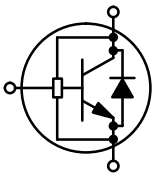
BUD44D2

Advance Information

High Speed, High Gain Bipolar NPN Power Transistor with Integrated Collector-Emitter Diode and Built-in Efficient Antisaturation Network

POWER TRANSISTORS
2 AMPERES
700 VOLTS
25 WATTS

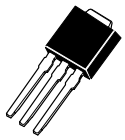


The BUD44D2 is state–of–art High Speed High gain BIPolar transistor (H2BIP). High dynamic characteristics and lot to lot minimum spread (±150 ns on storage time) make it ideally suitable for light ballast applications. Therefore, there is no need to guarantee an h_{FE} window.

Main features:

- Low Base Drive Requirement
- High Peak DC Current Gain (55 Typical) @ I_C = 100 mA
- **Extremely Low Storage Time Min/Max Guarantees Due to the H2BIP Structure which Minimizes the Spread**
- Integrated Collector–Emitter Free Wheeling Diode
- Fully Characterized and Guaranteed Dynamic $V_{CE(sat)}$
- "6 Sigma" Process Providing Tight and Reproductible Parameter Spreads

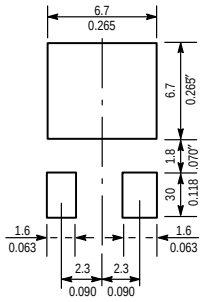
It's characteristics make it also suitable for PFC application.



CASE 369–07

CASE 369A–13

MINIMUM PAD SIZES RECOMMENDED FOR SURFACE MOUNTED APPLICATIONS



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Sustaining Voltage	V_{CEO}	400	Vdc
Collector–Base Breakdown Voltage	V_{CBO}	700	Vdc
Collector–Emitter Breakdown Voltage	V_{CES}	700	Vdc
Emitter–Base Voltage	V_{EBO}	12	Vdc
Collector Current — Continuous — Peak (1)	I_C I_{CM}	2 5	Adc
Base Current — Continuous — Peak (1)	I_B I_{BM}	1 2	Adc
*Total Device Dissipation @ T_C = 25°C *Derate above 25°C	P_D	25 0.2	Watt W/°C
Operating and Storage Temperature	T_J, T_{stg}	–65 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance — Junction to Case — Junction to Ambient	 $R_{\theta JC}$ $R_{\theta JA}$	 5 71.4	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8″ from case for 5 seconds	T_L	260	°C

(1) Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

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This document contains information on a new product. Specifications and information herein are subject to change without notice.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector–Emitter Sustaining Voltage (I_C = 100 mA, L = 25 mH)		$V_{CEO(sus)}$	400	470		Vdc
Collector–Base Breakdown Voltage (I_{CBO} = 1 mA)		V_{CBO}	700	920		Vdc
Emitter–Base Breakdown Voltage (I_{EBO} = 1 mA)		V_{EBO}	12	14.5		Vdc
Collector Cutoff Current (V_{CE} = Rated V_{CEO}, I_B = 0)	@ T_C = 25°C @ T_C = 125°C	I_{CEO}			50 500	μAdc
Collector Cutoff Current (V_{CE} = Rated V_{CES}, V_{EB} = 0) (V_{CE} = 500 V, V_{EB} = 0)	@ T_C = 25°C @ T_C = 125°C @ T_C = 125°C	I_{CES}			50 500 100	μAdc
Emitter–Cutoff Current (V_{EB} = 10 Vdc, I_C = 0)		I_{EBO}			100	μAdc
ON CHARACTERISTICS						
Base–Emitter Saturation Voltage (I_C = 0.4 Adc, I_B = 40 mAdc)	@ T_C = 25°C @ T_C = 125°C	$V_{BE(sat)}$		0.78 0.65	0.9 0.8	Vdc
(I_C = 1 Adc, I_B = 0.2 Adc)	@ T_C = 25°C @ T_C = 125°C			0.87 0.76	1 0.9	
Collector–Emitter Saturation Voltage (I_C = 0.4 Adc, I_B = 20 mAdc)	@ T_C = 25°C @ T_C = 125°C	$V_{CE(sat)}$		0.45 0.67	0.65 1	Vdc
(I_C = 0.4 Adc, I_B = 40 mAdc)	@ T_C = 25°C @ T_C = 125°C			0.25 0.27	0.4 0.5	
(I_C = 1 Adc, I_B = 0.2 Adc)	@ T_C = 25°C @ T_C = 125°C			0.28 0.35	0.5 0.6	
DC Current Gain (I_C = 0.4 Adc, V_{CE} = 1 Vdc)	@ T_C = 25°C @ T_C = 125°C	h_{FE}	20 18	32 26		—
(I_C = 1 Adc, V_{CE} = 1 Vdc)	@ T_C = 25°C @ T_C = 125°C		10 7	14 9.5		
(I_C = 2 Adc, V_{CE} = 5 Vdc)	@ T_C = 25°C		8	11		
DIODE CHARACTERISTICS						
Forward Diode Voltage (I_{EC} = 0.2 Adc)	@ T_C = 25°C	V_{EC}		0.8	1	V
(I_{EC} = 0.2 Adc)	@ T_C = 125°C			0.6		
(I_{EC} = 0.4 Adc)	@ T_C = 25°C			0.9	1.2	
(I_{EC} = 1 Adc)	@ T_C = 25°C			1.1	1.5	
Forward Recovery Time (see Figure 22 bis) (I_F = 0.2 Adc, di/dt = 10 A/μs)	@ T_C = 25°C	T_{fr}		415		ns
(I_F = 0.4 Adc, di/dt = 10 A/μs)	@ T_C = 25°C			390		
(I_F = 1 Adc, di/dt = 10 A/μs)	@ T_C = 25°C			340		

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic				Symbol	Min	Typ	Max	Unit
DYNAMIC SATURATION VOLTAGE								
Dynamic Saturation Voltage: Determined 1 µs and 3 µs respectively after rising I_{B1} reaches 90% of final I_{B1}	I_C = 0.4 A, I_{B1} = 40 mA, V_{CC} = 300 V	@ 1 µs	@ T_C = 25°C	$V_{CE(dsat)}$		3.3		V
			@ T_C = 125°C			6.8		
		@ 3 µs	@ T_C = 25°C			0.5		
			@ T_C = 125°C			1.3		
	I_C = 1 A, I_{B1} = 0.2 A, V_{CC} = 300 V	@ 1 µs	@ T_C = 25°C			4.4		
			@ T_C = 125°C			12.8		
		@ 3 µs	@ T_C = 25°C			0.5		
			@ T_C = 125°C			1.8		
DYNAMIC CHARACTERISTICS								
Current Gain Bandwidth (I_C = 0.5 Adc, V_{CE} = 10 Vdc, f = 1 MHz)				f_T		13		MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 1 MHz)				C_{ob}		50	75	pF
Input Capacitance (V_{EB} = 8 Vdc)				C_{ib}		240	500	pF
SWITCHING CHARACTERISTICS: Resistive Load (D.C. ≤ 10%, Pulse Width = 40 µs)								
Turn–on Time	I_C = 1 Adc, I_{B1} = 0.2 Adc, I_{B2} = 0.5 Adc, V_{CC} = 300 Vdc		@ T_C = 25°C	t_{on}		90	150	ns
			@ T_C = 125°C			105		
Turn–off Time			@ T_C = 25°C	t_{off}		1.1	1.25	µs
			@ T_C = 125°C			1.5		
Turn–on Time	I_C = 0.5 Adc, I_{B1} = 50 mAdc, I_{B2} = 250 mAdc, V_{CC} = 300 Vdc		@ T_C = 25°C	t_{on}	400		600	ns
			@ T_C = 125°C			600		
Turn–off Time			@ T_C = 25°C	t_{off}	750		1000	ns
			@ T_C = 125°C			1300		
SWITCHING CHARACTERISTICS: Inductive Load (V_{clamp} = 300 V, V_{CC} = 15 V, L = 200 µH)								
Fall Time	I_C = 0.4 Adc, I_{B1} = 40 mAdc, I_{B2} = 0.2 Adc		@ T_C = 25°C	t_f		110	150	ns
			@ T_C = 125°C			105		
Storage Time			@ T_C = 25°C	t_s		0.55	0.75	µs
			@ T_C = 125°C			0.7		
Crossover Time			@ T_C = 25°C	t_c		85	150	ns
			@ T_C = 125°C			80		
Fall Time	I_C = 1 Adc, I_{B1} = 0.2 Adc, I_{B2} = 0.5 Adc		@ T_C = 25°C	t_f		100	150	ns
			@ T_C = 125°C			90		
Storage Time			@ T_C = 25°C	t_s		1.05	1.5	µs
			@ T_C = 125°C			1.45		
Crossover Time			@ T_C = 25°C	t_c		100	175	ns
			@ T_C = 125°C			100		
Fall Time	I_C = 0.8 Adc, I_{B1} = 160 mAdc, I_{B2} = 160 mAdc		@ T_C = 25°C	t_f		110	150	ns
			@ T_C = 125°C			180		
Storage Time			@ T_C = 25°C	t_s	2.05		2.35	µs
			@ T_C = 125°C			2.8		
Crossover Time			@ T_C = 25°C	t_c		180	300	ns
			@ T_C = 125°C			400		
Fall Time	I_C = 0.4 Adc, I_{B1} = 40 mAdc, I_{B2} = 40 mAdc		@ T_C = 25°C	t_f		150	225	ns
			@ T_C = 125°C			175		
Storage Time			@ T_C = 25°C	t_s	1.65		1.95	µs
			@ T_C = 125°C			2.2		
Crossover Time			@ T_C = 25°C	t_c		150	250	ns
			@ T_C = 125°C			330		

TYPICAL STATIC CHARACTERISTICS

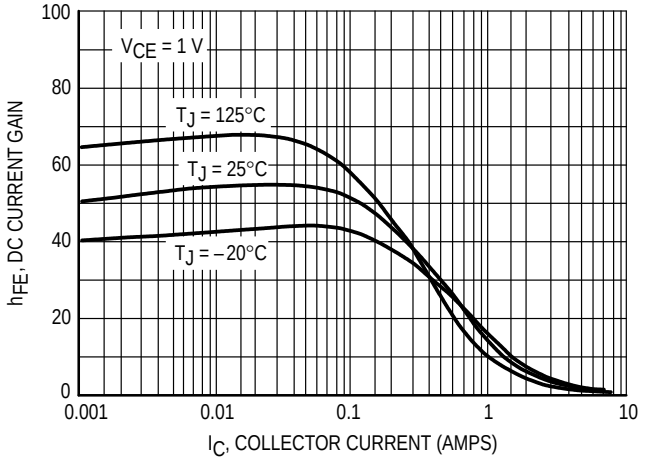


Figure 1. DC Current Gain @ 1 Volt

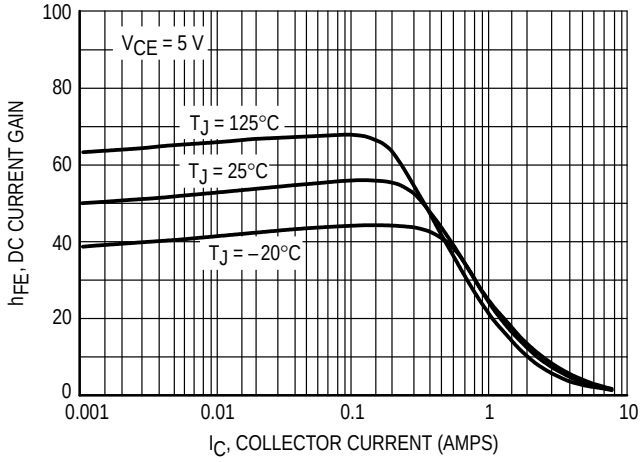


Figure 2. DC Current Gain @ 5 Volt

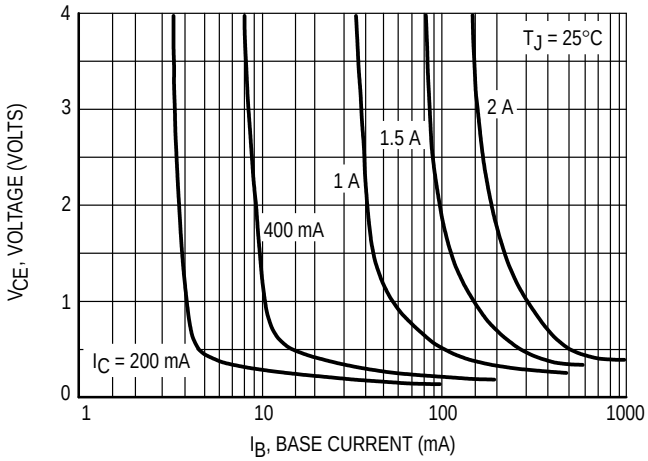


Figure 3. Collector Saturation Region

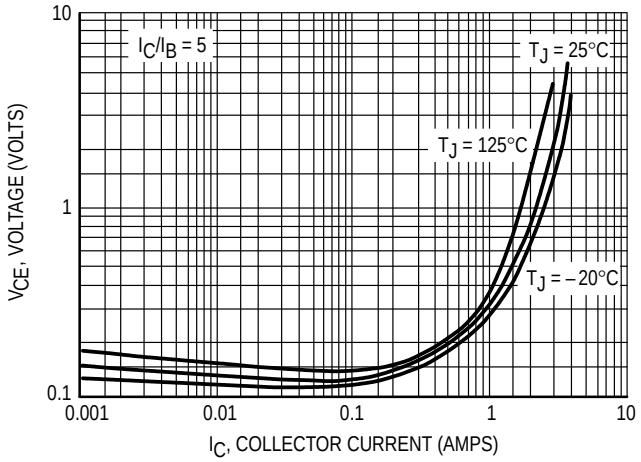


Figure 4. Collector–Emitter Saturation Voltage

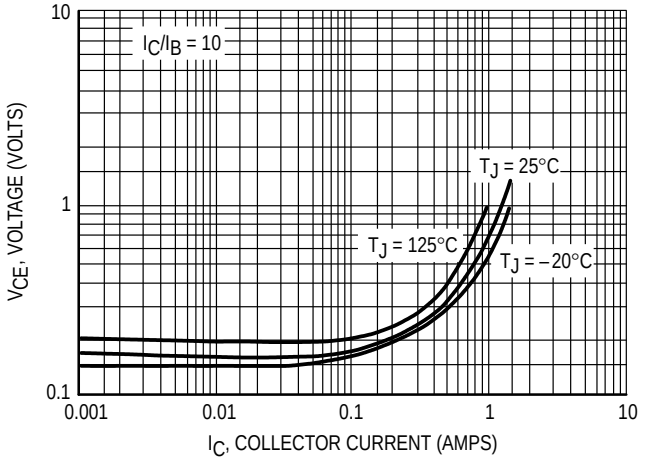


Figure 5. Collector–Emitter Saturation Voltage

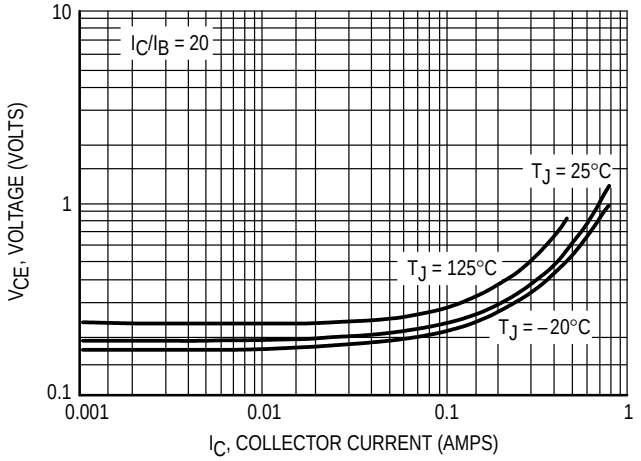


Figure 6. Collector–Emitter Saturation Voltage

TYPICAL STATIC CHARACTERISTICS

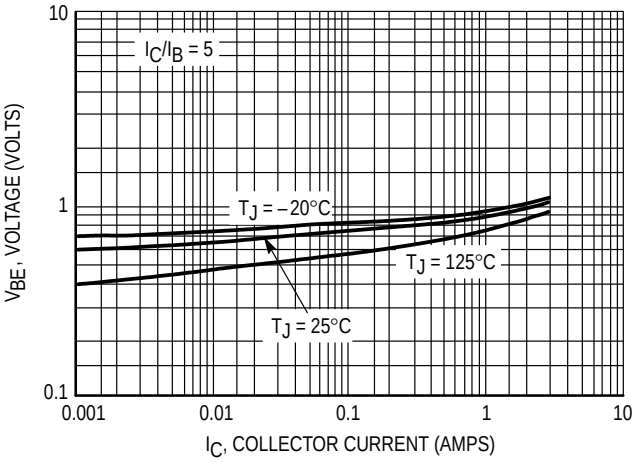


Figure 7A. Base–Emitter Saturation Region

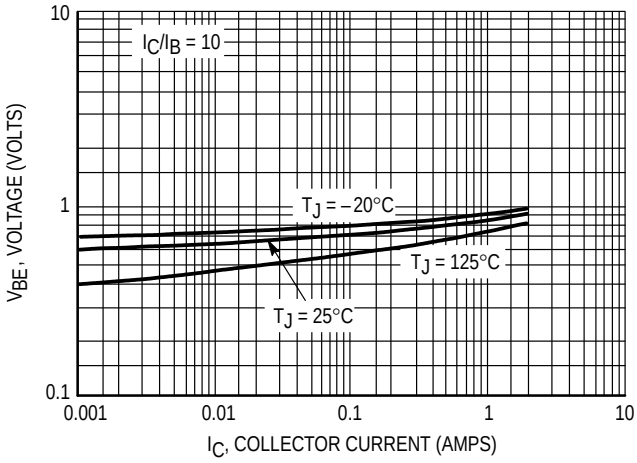


Figure 7B. Base–Emitter Saturation Region

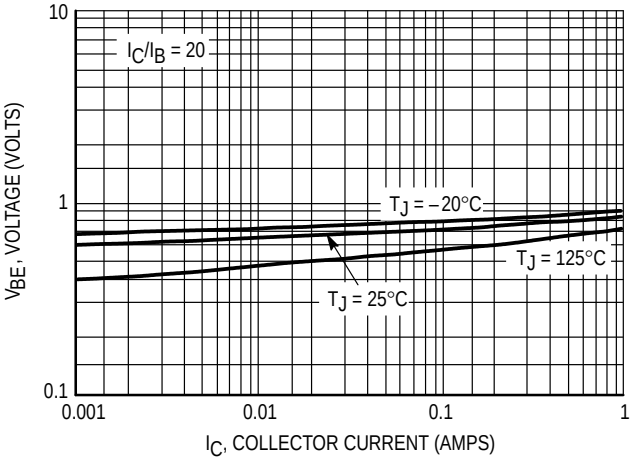


Figure 7C. Base–Emitter Saturation Region

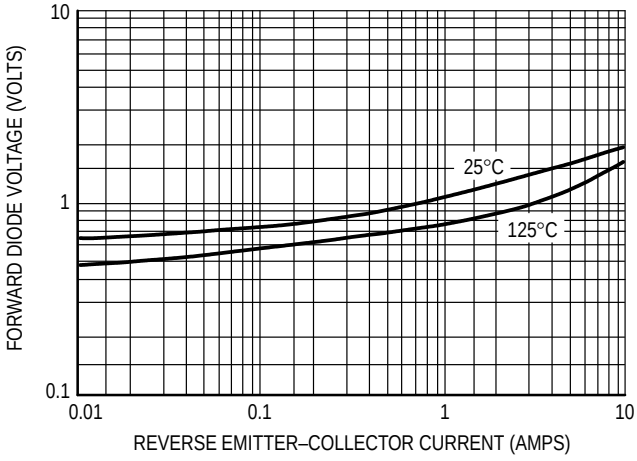


Figure 8. Forward Diode Voltage

TYPICAL SWITCHING CHARACTERISTICS

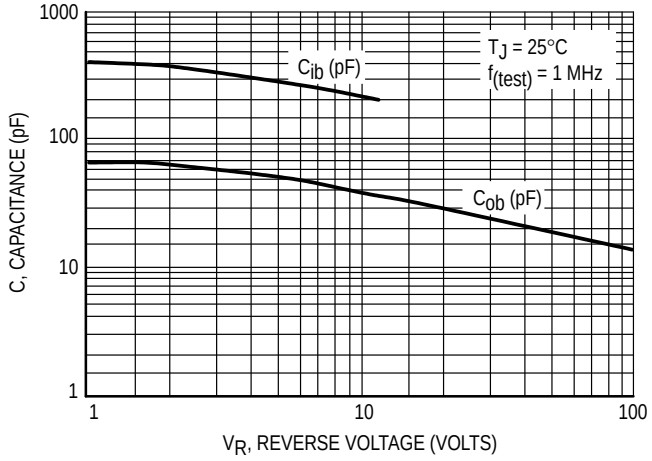


Figure 9. Capacitance

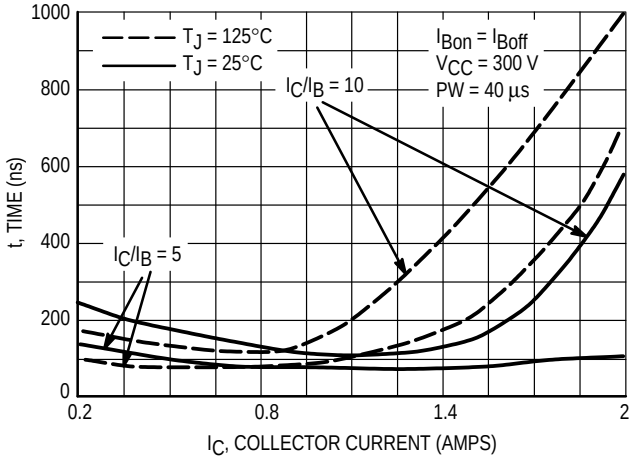


Figure 10. Resistive Switch Time, t_{on}

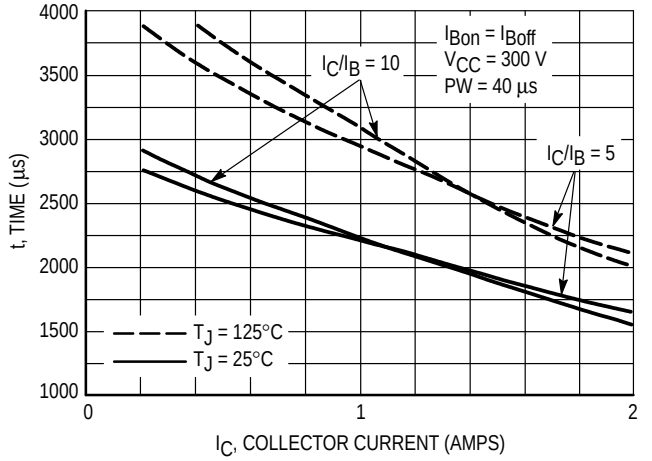


Figure 11. Resistive Switch Time, t_{off}

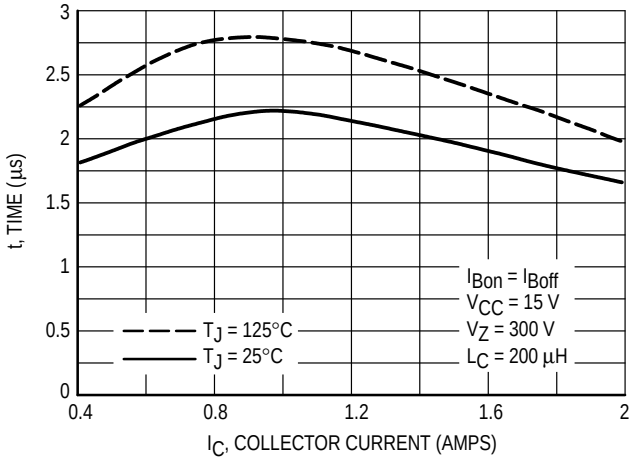


Figure 12. Inductive Storage Time, t_{si} @ I_C/I_B = 5

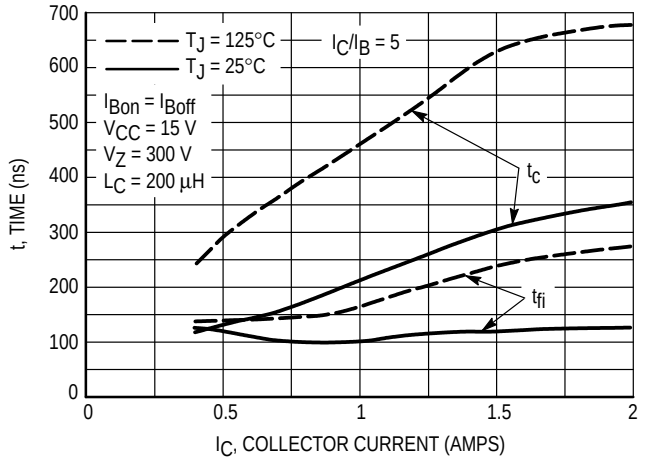


Figure 13. Inductive Switching, t_c & t_{fi} @ I_C/I_B = 5

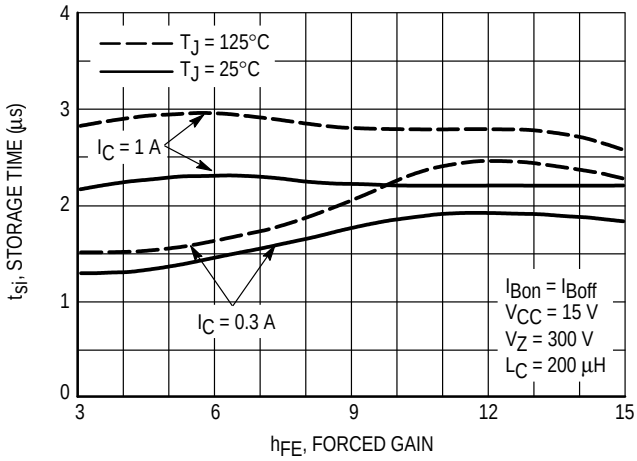


Figure 14. Inductive Storage Time

TYPICAL SWITCHING CHARACTERISTICS

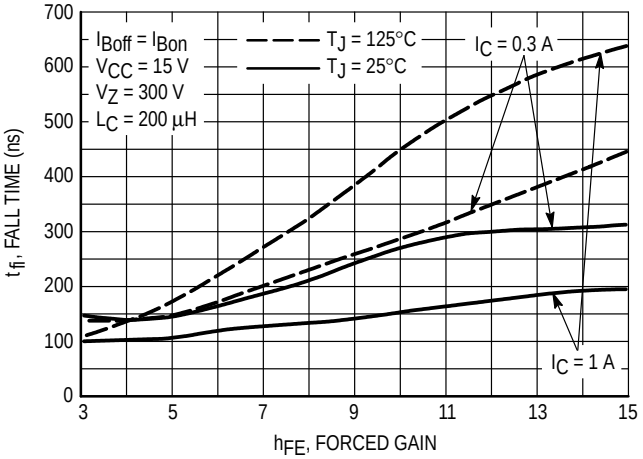


Figure 15. Inductive Fall Time

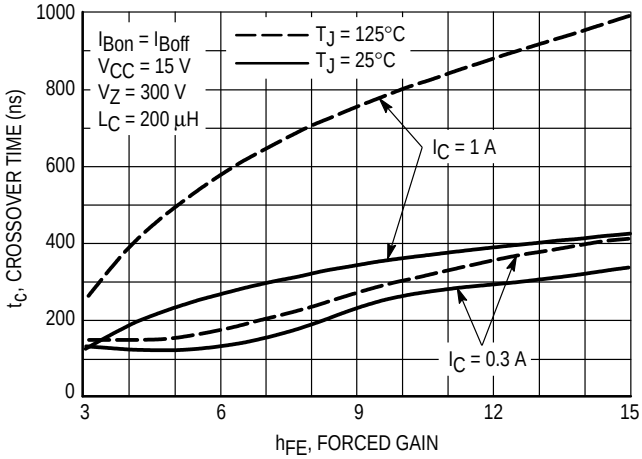


Figure 16. Inductive Crossover Time

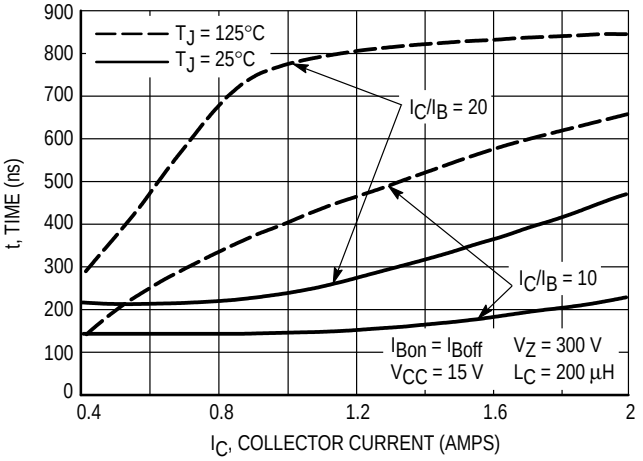


Figure 17. Inductive Switching, t_{fi}

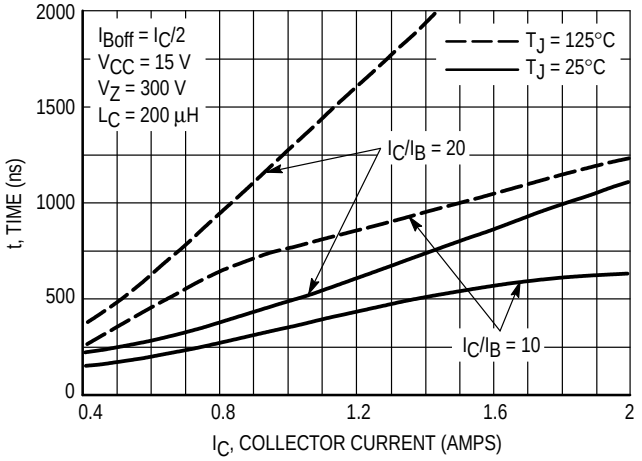


Figure 18. Inductive Switching, t_c

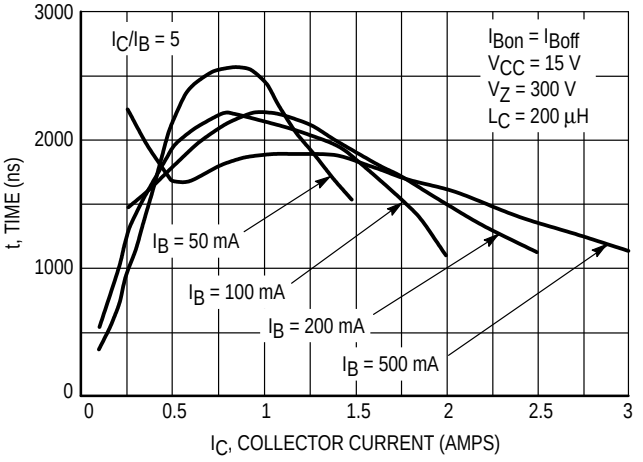


Figure 19. Inductive Storage Time, t_{si}

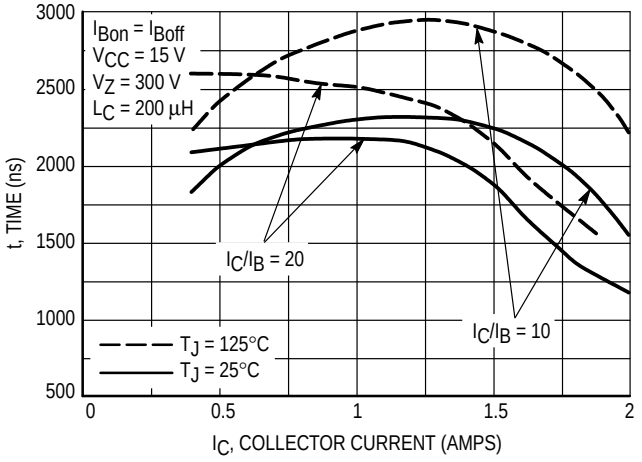


Figure 20. Inductive Storage Time, t_{si}

TYPICAL SWITCHING CHARACTERISTICS

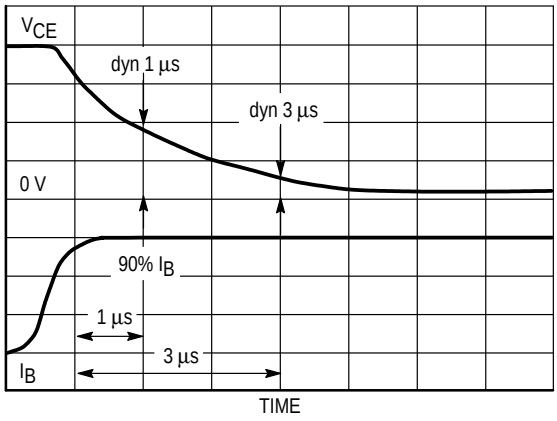


Figure 21. Dynamic Saturation Voltage Measurements

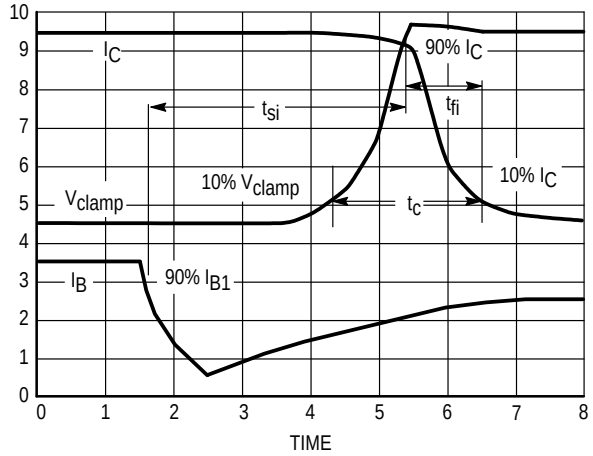


Figure 22. Inductive Switching Measurements

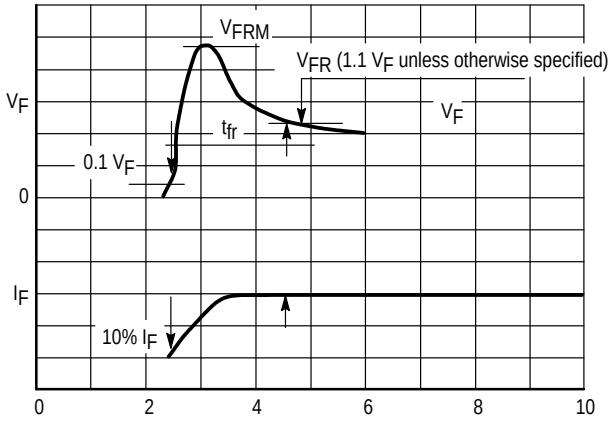
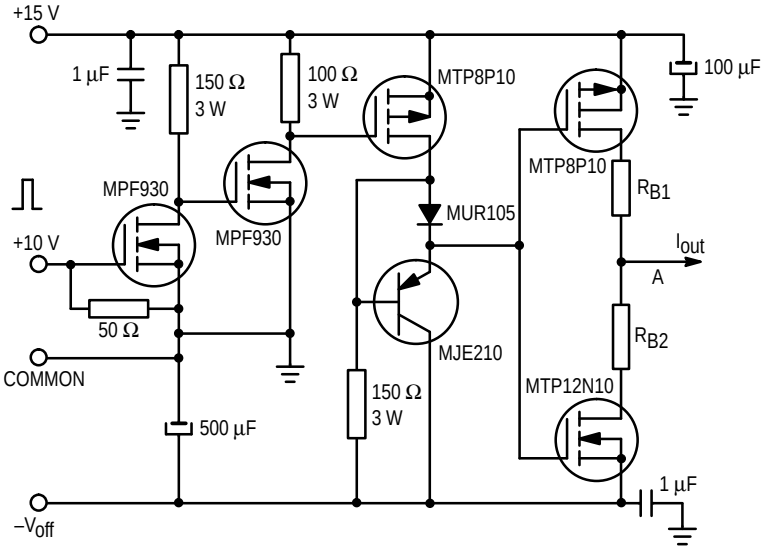
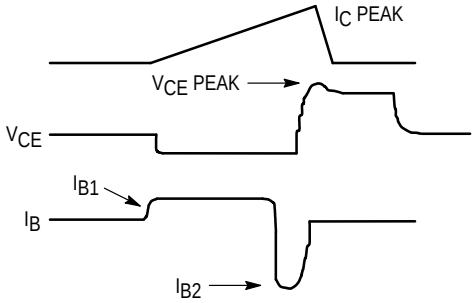


Figure 22 bis. t_{fr} Measurements

TYPICAL SWITCHING CHARACTERISTICS

Table 1. Inductive Load Switching Drive Circuit





$V_{(BR)CEO(sus)}$	Inductive Switching	RBSOA
L = 10 mH	L = 200 μH	L = 500 μH
R_{B2} = ∞	R_{B2} = 0	R_{B2} = 0
V_{CC} = 20 Volts	V_{CC} = 15 Volts	V_{CC} = 15 Volts
$I_{C(pk)}$ = 100 mA	R_{B1} selected for desired I_{B1}	R_{B1} selected for desired I_{B1}

TYPICAL STATIC CHARACTERISTICS

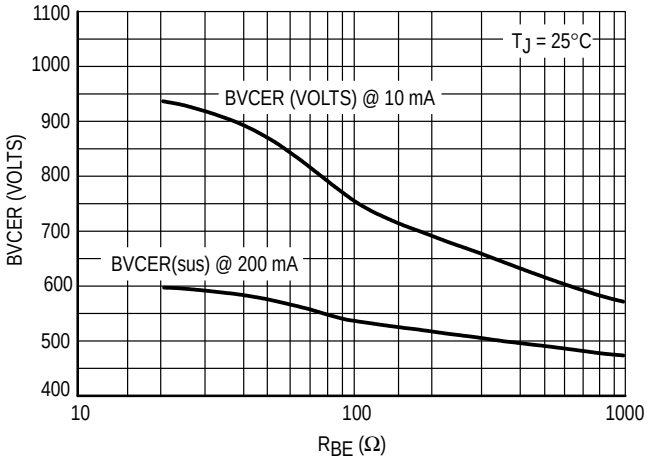


Figure 23. BVCER

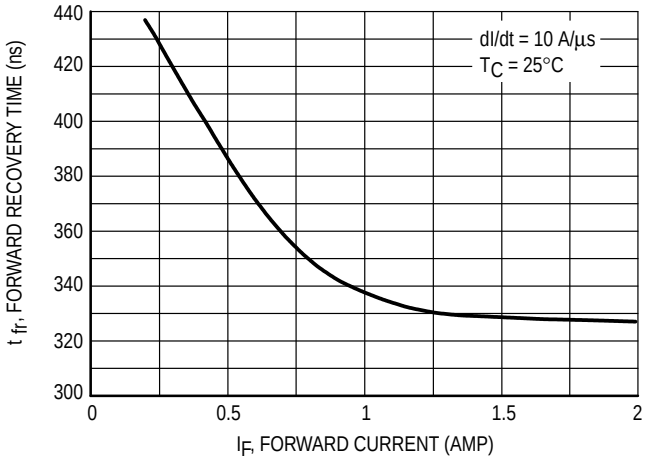
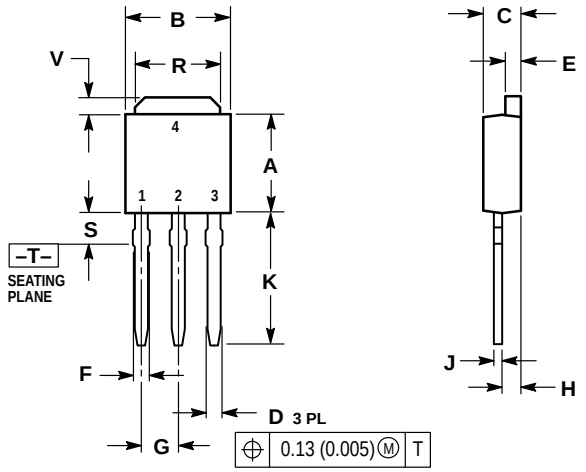


Figure 24. Forward Recovery Time t_{fr}

PACKAGE DIMENSIONS

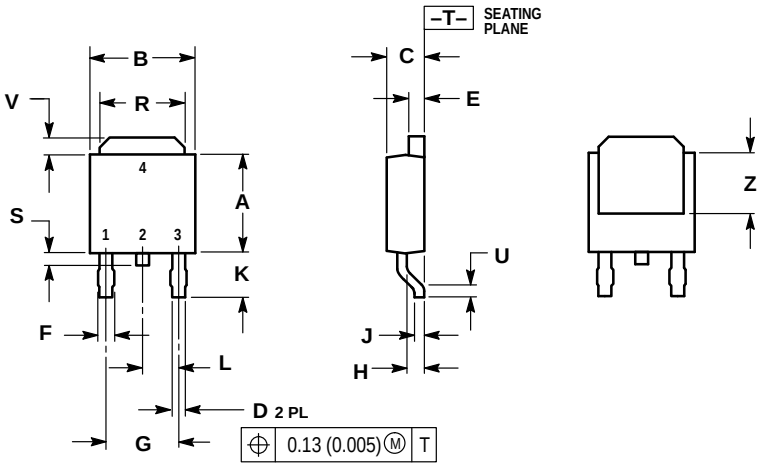


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1.27

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

CASE 369–07
ISSUE K



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	—	0.51	—
V	0.030	0.050	0.77	1.27
Z	0.138	—	3.51	—

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

CASE 369A–13
ISSUE W

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